TB1S-10~TB10S-10

Rev.C Feb.-2015

蓝箭电子
BLUE ROCKET ELECTRONICS

DATA SHEET

描述 / Descriptions

1A 表面贴装玻璃钝化整流桥，薄型 ABS/LBF 封装。
1A Surface Mount Glass Passivated Bridge Rectifier, ABS/LBF thin package.

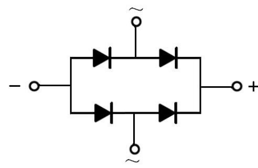
特征 / Features

玻璃钝化芯片，反向电压：100V~1000V，正向电流：1.0A，浪涌电流大，适用表面贴装。无卤产品。
Glass Passivated Chip Junction, Reverse Voltage :100 to 1000V,Forward Current: 1.0A,High Surge Current Capability, Designed for Surface Mount Application. Halogen free product.

用途 / Applications

一般用途.
General purpose.

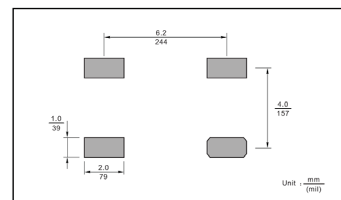
内部等效电路 / Equivalent Circuit



引脚排列 / Pinning

PIN	DESCRIPTION
1	Input Pin (~)
2	Input Pin (~)
3	Output Anode (+)
4	Output Cathode (-)

The recommended mounting pad size



印章代码 / Marking

见印章说明。See Marking Instructions.

极限参数 / Absolute Maximum Ratings(Ta=25℃)

参数 Parameter	符号 Symbol	数值 Rating						单位 Unit
		TB1S-10	TB2S-10	TB4S-10	TB6S-10	TB8S-10	TB10S-10	
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	100	200	400	600	800	1000	V
Maximum RMS voltage	V_{RMS}	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	V_{DC}	100	200	400	600	800	1000	V
Average Rectified Output Current at Ta = 50℃	I_o	1.0						A
Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load (JEDEC Method)	I_{FSM}	35						A
Typical Junction Capacitance（Note1）	C_j	13						pF
Typical Thermal Resistance（Note2）	$R_{θJA}$	80						℃/W
	$R_{θJL}$	25						℃/W
Junction Temperature, Storage Temperature Range	T_j,T_{stg}	-55~150						℃

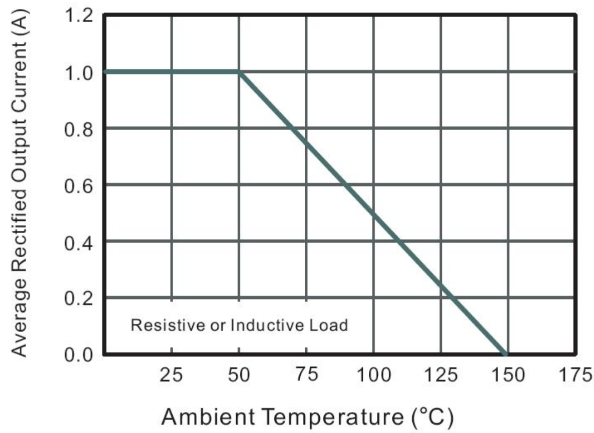
Note:

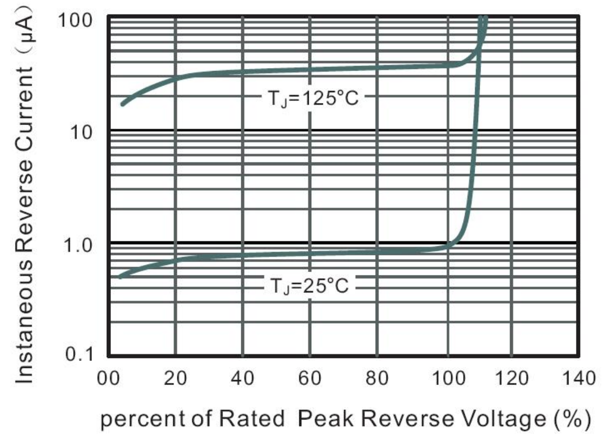
1. Measured at 1MHz and applied reverse voltage of 4 V D.C.
2. Mounted on glass epoxy PC board with 4×(5×5mm^2 ） copper pad..

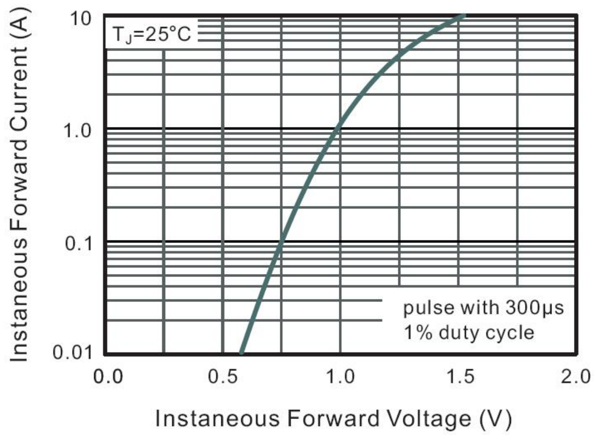
电性能参数 / Electrical Characteristics(Ta=25℃)

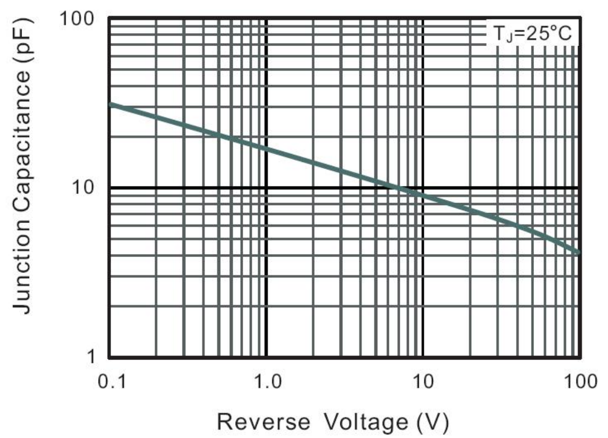
参数 Parameter	符号 Symbol	测试条件 Test Conditions	数值 Rating	单位 Unit
Forward Voltage per element	V_F	I_F=1.0A	1.1	V
Maximum DC Reverse Current at Maximum DC Blocking Voltage	I_R	T_a=25℃	5.0	μA
		T_a=100℃	50	μA
		T_a=125℃	100	μA

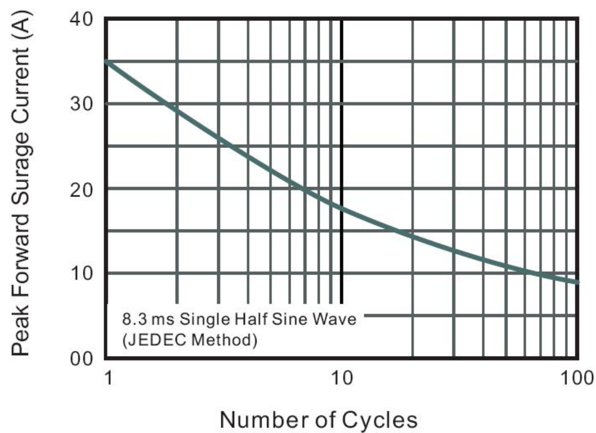
电参数曲线图 / Electrical Characteristic Curve





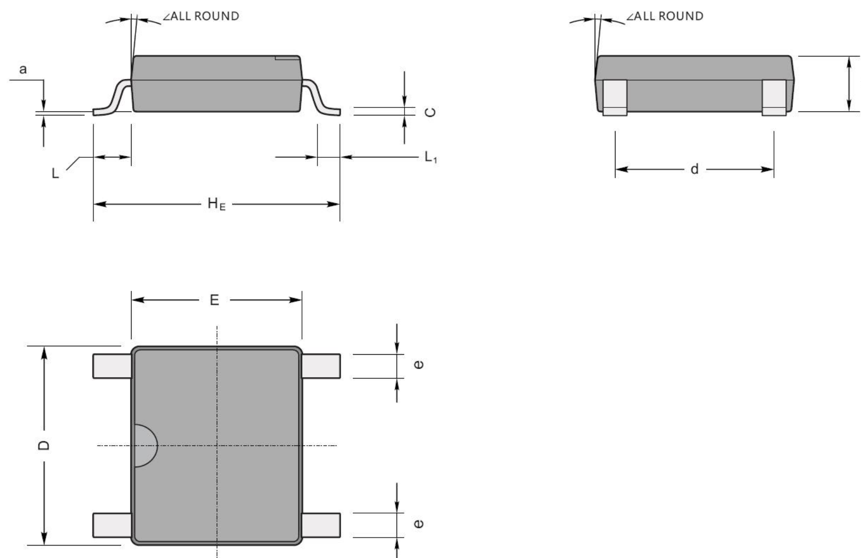






外形尺寸图 / Package Dimensions

ABS/LBF



ABS/LBF mechanical data

<table>
<tr><th>UNIT</th><th></th><th>A</th><th>C</th><th>D</th><th>E</th><th>H_E</th><th>d</th><th>e</th><th>L</th><th>L₁</th><th>a</th><th>∠</th></tr>
<tr><td rowspan="2">mm</td><td>max</td><td>1.5</td><td>0.22</td><td>5.2</td><td>4.5</td><td>6.4</td><td>4.2</td><td>0.7</td><td rowspan="2">0.95</td><td rowspan="2">0.6</td><td rowspan="2">0.2</td><td rowspan="4">7°</td></tr>
<tr><td>min</td><td>1.3</td><td>0.15</td><td>4.9</td><td>4.2</td><td>6.0</td><td>3.8</td><td>0.5</td></tr>
<tr><td rowspan="2">mil</td><td>max</td><td>59</td><td>8.7</td><td>205</td><td>177</td><td>252</td><td>165</td><td>28</td><td rowspan="2">37</td><td rowspan="2">24</td><td rowspan="2">4</td></tr>
<tr><td>min</td><td>51</td><td>5.9</td><td>193</td><td>166</td><td>236</td><td>150</td><td>20</td></tr>
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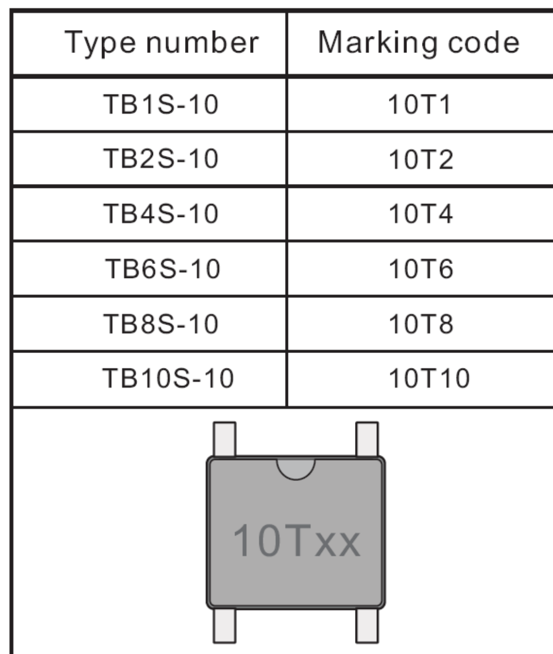
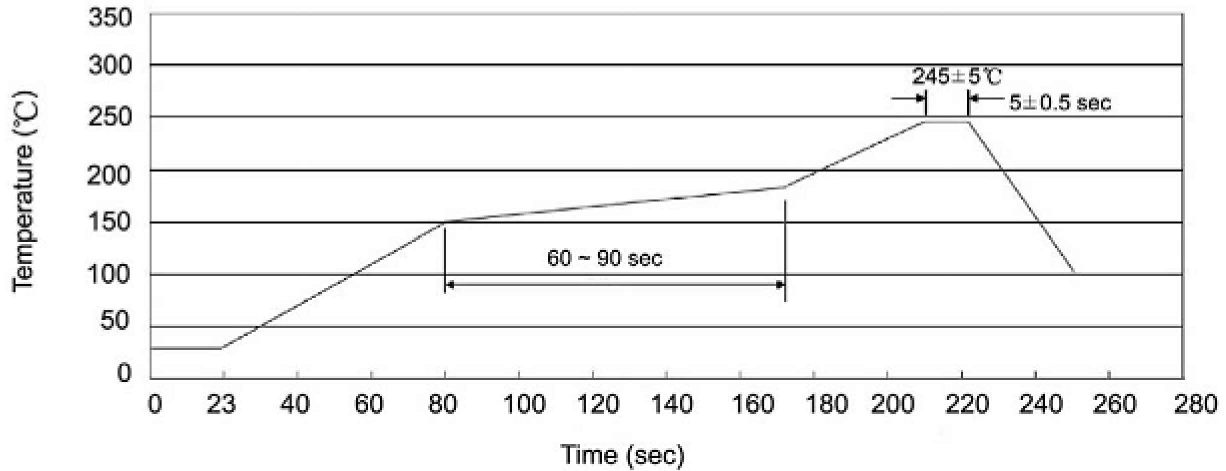
印章说明 / Marking Instructions

Marking



Type number	Marking code
TB1S-10	10T1
TB2S-10	10T2
TB4S-10	10T4
TB6S-10	10T6
TB8S-10	10T8
TB10S-10	10T10

回流焊温度曲线图(无铅) / Temperature Profile for IR Reflow Soldering(Pb-Free)



说明：

1、预热温度 25～150℃，时间 60～90sec;

2、峰值温度 245±5℃，时间持续为 5±0.5sec;

3、焊接制程冷却速度为 2～10℃/sec.

Note:

1.Preheating:25~150℃, Time:60~90sec.

2.Peak Temp.:245±5℃, Duration:5±0.5sec.

3. Cooling Speed: 2~10℃/sec.

耐焊接热试验条件 / Resistance to Soldering Heat Test Conditions

温度：260±5℃　　时间：10±1 sec.

Temp.:260±5℃　　Time:10±1 sec

包装规格 / Packaging SPEC.

卷盘包装 / REEL

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm^3)		
	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel	Inner Box 盒	Outer Box 箱
ABS/LBF	5000	2	10000	5	50000	13″ ×15	336X336X40	345X345X235

使用说明 / Notices